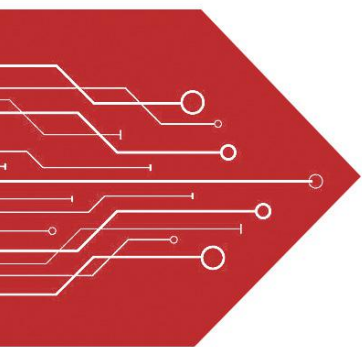


MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



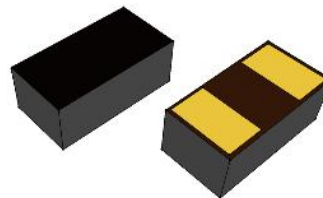
PLED

Product data sheet

Features

- Ultra-Low capacitance:0.05pF(typ.)
- Low leakage current(<10nA)
- Fast response time(<1ns)
- Bi-directional,single line protection
- IEC 61000-4-2 (ESD Air): 15kV
IEC 61000-4-2 (ESD Contact): 8kV

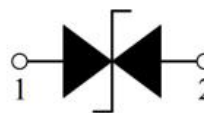
Pin Description



Applications

- USB 3.0/3.1
- HDMI 1.3/1.4/2.0
- RF Antenna
- SATA and eSATA Interface

Schematic Diagram



Order Information

Type	Package	Size (mm)	Delivery Form	Delivery Quantity
MSPESD06DMA05	0603	1.60x0.80x0.40	7" T&R	5,000

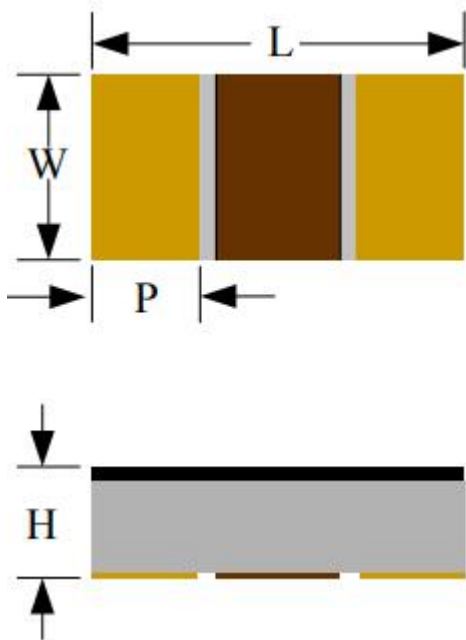
Limiting Values($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

Symbol	Parameter	Conditions	Min	Max	Unit
V_{ESD}	Electrostatic Discharge Voltage	IEC 61000-4-2; Contact Discharge	-	8	kV
		IEC 61000-4-2; Air Discharge	-	15	kV
T_A	Operating Temperature Range	-	-55	125	$^{\circ}\text{C}$
T_{stg}	Storage Temperature Range	-	-40	85	$^{\circ}\text{C}$

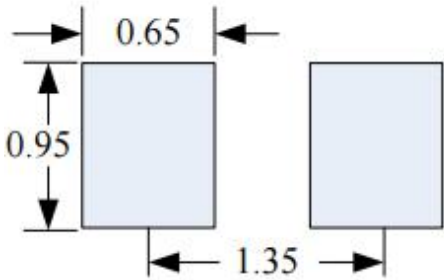
Electrical Characteristics($T_A = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Min	Typ.	Max	Unit
V_{DC}	Continuous Operating Voltage	-	-	-	5.0	V
V_T	Trigger Voltage	IEC61000-4-2 8kV contact discharge	-	450	-	V
V_C	Clamping Voltage	IEC61000-4-2 8kV contact discharge	-	40	-	V
I_L	Leakage Current	DC 5V shall be applied on component	-	-	10	nA
C_J	Capacitance	Measured at 10MHz	-	0.05	-	pF

Package Dimension



Recommended Solder Pad Footprint



***Sizes in mm**

Notes:
This solder pad layout is for reference purposes only.

Dimension	Unit: Millimeters	
	Min.	Max.
L	1.45	1.75
W	0.70	0.95
P	0.20	0.50
H	0.26	0.46

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